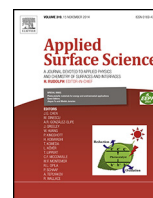




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## Ar ions irradiation effects in ZrN thin films grown by pulsed laser deposition

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### ABSTRACT

Thin ZrN films (<500 nm) were grown on (100)Si substrates at a substrate temperature of 500 °C by the pulsed laser deposition (PLD) technique using a KrF excimer laser under CH<sub>4</sub> or N<sub>2</sub> atmosphere. Glancing incidence X-ray diffraction showed that films were nanocrystalline, while X-ray reflectivity studies indicated that the films were very dense and with a smooth surface. The films were used to study the effect of 800 keV Ar ion irradiation on their structure and properties. After irradiation with a dose of 10<sup>14</sup> at/cm<sup>2</sup> the lattice parameter and crystallites size did marginally change. However, after irradiation with a 10<sup>15</sup> at/cm<sup>2</sup> dose, a clear increase in the lattice parameter accompanied by a significant decrease in nanohardness and Young modulus were observed.

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### 1. Introduction

Zirconium nitride, ZrN, possesses both ceramic and metallic characteristics: very high melting point [1], high hardness (30–35 GPa) [2,3], good wear resistance [4], high thermochemical stability [5], low electrical resistivity [6], and good biocompatibility [7]. In addition, because of its low cross section capture for neutrons it could be used as a protective coating for nuclear application. Several techniques have been employed to obtain high quality ZrN thin films to investigate their properties [2–8]. Pulsed laser deposition (PLD) technique is very suitable for such studies, since by controlling the laser irradiation parameters and deposition conditions films with various structural qualities and Zr/N values could be obtained [3,9,10]. Moreover, such films could be deposited at moderate substrate temperatures, below 550 °C [9,10]. We showed previously that such PLD grown ZrN films exhibited high hardness and Young modulus values and low friction coefficients and wear rates [10].

The effect of Ar ion irradiation on films has been studied since it is able to qualitatively described disorder induced by neutron irradiation at the micrometer-scale. On the atomic level, on the

other hand, the main interest of irradiation lies in the fact that many defects can be created without modifying the chemistry of the material. This work tries to qualitatively estimate the impact of radiation damages produced in nuclear plants in this materials, a potential candidate for liners of IV generation nuclear plants. It is focused on the investigation of structural and mechanical properties of such thin films combining several investigations techniques in order to understand the link between structural damage caused by irradiation and mechanical properties in ceramics films.

### 2. Experimental details

The PLD experimental set up used to deposit the films has been previously described [9,10]. A KrF excimer laser ( $\lambda = 248$  nm, pulse duration  $\tau = 25$  ns, 8 J/cm<sup>2</sup> fluence, 40 Hz repetition rate) is used to ablate a ZrN target in a stainless steel chamber. The films were deposited on p<sup>++</sup> (100)Si substrates (MEMC Electronic Materials, Inc.) at a nominal substrate temperature of 500 °C under a high purity atmosphere of CH<sub>4</sub> or N<sub>2</sub>. Previous results indicated that a low gas pressure during deposition had a beneficial effect on the structure of the deposited films. CH<sub>4</sub> was also used besides N<sub>2</sub> since the incorporation of small amounts of C in the ZrN lattice resulted in slightly better mechanical properties [10]. The deposition conditions are displayed in Table 1.

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**Table 1**  
Deposition conditions and structural properties of the deposited films.

Sample	Atmosphere (Pa)	Number of pulses	Lattice parameter (Å)		Density (g/cm <sup>3</sup> )		Surface roughness, RMS (Å)	Grain size (Å)	Micro-strain (%)
			XRD	GIXRD	XRR	GIXRD			
ZrN1	$2 \times 10^{-3}$ CH <sub>4</sub>	20,000	4.684	4.543	7.09	7.406	6/4	110	0.9
ZrN3	$2 \times 10^{-3}$ N <sub>2</sub>	20,000	4.667	4.546	7.05	7.387	7/5	155	1.3

The deposited ZrN films were irradiated at room temperature by 800 keV Ar ions at a flux of  $10^{11}$  cm<sup>-2</sup> s<sup>-1</sup>. The kinetic energy of Ar ions was chosen to maximize the nuclear energy loss inside the ZrN layer, the electronic energy loss being one order of magnitude smaller than the nuclear energy loss. The displacement per atom (dpa) value was calculated from SRIM integrating all displacements induced by atomic collision between Ar atoms and zirconium and nitrogen but also collisions between nitrogen and zirconium atoms with atoms at rest in the crystal. As pointed out by the SRIM simulations, atomic mixing occurred at the ZrN/Si interface. However, the characteristic length of this mixing calculated from the Si penetration into the ZrN layer remained smaller than five nanometers. The amount of Si in the ZrN layer was equal to 0.04 atomic fraction for the highest fluence used here ( $10^{15}$  cm<sup>-2</sup>). Both the mixing length as well as the atomic concentration remained relatively small and did not play an important part in XRD and reflectivity measurements.

For all studied samples, the displacement rate was equal to  $4.6 \cdot 10^{-4}$  dpa/s. Two distinct irradiations were performed at 4.6 dpa and 46 dpa (with fluences of  $10^{14}$  and  $10^{15}$  cm<sup>-2</sup>) in order to study the impact of radiation damages on the structure and mechanical properties of ZrN thin films. The temperature during irradiation was monitored by a thermocouple stuck on the back of the sample avoiding radiation damages on it. No important variation of the temperature was measured during irradiations, suggesting that the temperature increasing was smaller than 50 K for all performed irradiations. To study the structural evolution (unit cell parameters, space group evolution) and microstructural evolution (sizes of Coherent Diffracting Domains, CDD, micro strain induced by radiation damages), glancing incidence X-ray diffraction (GIXRD) investigations were performed on the films. The use of the GIXRD technique to collect diffraction patterns from thin films was described in details in previous works [11,12] and successfully applied to study radiation damage in irradiated materials [13,14]. Within the glancing incidence technique, diffraction patterns are collected from crystallites that have the planes tilted at a certain angle with respect to the surface normal.

From calculations of the X-ray beam penetration depth versus the incidence angle a value of 1°, which gives an X-ray penetration depth of 400 nm inside the ZrC sample, was selected for the incidence angle for all measurements. This value was chosen for a twofold reason. First of all, it is associated with the maximum of damage peak in the material as pointed out in Fig. 3. On the other hand, we assumed that mechanical or chemical effects due to lattice misfit between the Si(1 0 0) wafer and the ZrN film were negligible.

The films mass density, thickness, and surface roughness were obtained from simulations of the XRR curves using a commercially available model (X'Pert Reflectivity) consisting of three layers: interfacial layer, accounting for the silicon native oxide and any ions that were subplanted/mixed within this layer [8,15,16], the deposited nitride layer and a surface contamination layer accounting for the hydroxide/carbon layer present at the topmost surface when films were exposed to the ambient. Atomic force microscopy (AFM) and scanning electron microscopy (SEM) were also used to investigate the surface morphology of the deposited samples.

The mechanical properties of the thin films were investigated using a Hysitron TI900 Triboindenter with a 100 nm diamond

Berkovich tip. Tip area calibration was performed on a standard fused silica sample before the test. The indentation experiments were performed in quasi-static indentation mode, with maximum load of 1000 μN. A 4 × 4 array of 16 indents, 5 μm apart from each other was done on each sample. The loading, hold, and unloading times were 10, 3, and 10 s respectively. To minimize substrate contributions, the hardness and reduced modulus were determined from load-displacement contact depths between 30 and 50 nm following the model of Oliver and Pharr [17].

### 3. Results and discussion

According to GIXRD and XRR results, which are included in Table 1, the deposited films were nanocrystalline, dense and with a low surface roughness [9]. Symmetrical XRD scans showed that films were slightly (1 1 1) textured, a typical texture for rock-salt type structures, where (1 1 1) planes have the highest atomic density. Williamson–Hall plots were used to estimate the crystallite sizes and micro-strain values [10], which are also displayed in Table 1. The rather large values estimated for the micro-strain were caused by defects induced by energetic ions and atoms from the plasma that bombarded the growing film during deposition [8,15,16]. The difference between the lattice parameter values extracted from symmetrical scans (out of plane) versus those extracted from GIXRD scans (in plane) was caused by the presence of a compressive stress in the deposited films [8–10].

The density estimated from XRR simulations was significantly lower than that estimated from GIXRD results, which correspond to fully stoichiometric compounds. First of all, since the films were under compressive stress the in plane lattice parameter was larger than the out of plane parameter (see Table 2). Secondly, this suggests that the as-deposited films already contain vacancies. The very smooth surface of the deposited films indicated by the results of XRR curves simulations was confirmed by the AFM and SEM investigations, as shown in Figs. 1 and 2. The very dense structure and small crystallite size is also evident in the SEM image of a cross section of a fractured ZrN film.

In order to simulate radiation damages induced by 800 keV Ar ions in the ZrN thin layer, the penetration depth of Ar impinging ions as well as the number of Zr and N vacancies created in two distinct sub lattices were calculated within the binary collision framework (STRIM code) and displayed in Fig. 3. The displacement threshold energies were equal to 25 and 28 eV for Zr and N sub lattices in all simulations. The sputtering yield was equal to 0.7 and 1.6 at/ion for Zr and N sublattices. This implies that the sputtering occurring at the ZrN surface was equal to 0.1 and 1.6 nanometers for each sublattice for the most irradiated sample associated with a fluence of  $10^{15}$  cm<sup>-2</sup>, which is negligible and does not induce craters, able to increase drastically the roughness of the ZrN surface and then the slope of reflectivity curves after irradiation.

The nature and the energy of the impinging atoms ions were selected to obtain profiles of vacancies produced in two sub lattices that are relatively uniform along the thickness of the film as shown in Fig. 3. Such a distribution of vacancies ensures the avoidance of any spurious effects due to a damage gradient. On the other hand, we have calculated the atomic fraction of Ar ions implanted in the thin film, which is also plotted in Fig. 3 (green curve). This

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